

**APPLICATION DATA SHEET**

**APPLICATION INFORMATION**

Application Number::	Not Yet Assigned
Filing Date::	Filed Concurrently Herewith
Application Type::	Regular
Subject Matter::	Utility
CD-ROM or CD-R?::	None
Computer Readable Form (CRF)?::	No
Title::	HARDENABLE PRESSURE SENSITIVE ADHESIVE SHEET FOR DICING/DIE-BONDING AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE
Attorney Docket Number::	1217-053827
Request for Early Publication?::	No
Request for Non-Publication?::	No
Small Entity?::	No
Secrecy Order In Parent Appl.?::	No

**APPLICANT INFORMATION**

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Naoya
Family Name::	SAIKI
City of Residence::	Koshigaya-shi
State or Province of Residence::	Saitama
Country of Residence::	Japan
Street of Mailing Address::	1-148-1-203, Miyamoto-cho
City of Mailing Address::	Koshigaya-shi
State or Province of Mailing Address::	Saitama
Country of Mailing Address::	Japan
Postal or Zip Code of Mailing Address::	3430806

**CORRESPONDENCE INFORMATION**

Correspondence Customer Number:: 28289

**REPRESENTATIVE INFORMATION**

Representative Customer Number::	28289	
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**FOREIGN PRIORITY INFORMATION**

Country::	Application number::	Filing Date::	Priority Claimed::
WIPO	PCT/JP2004/009629	July 7, 2004	Yes
JP	2003-271950	July 8, 2003	Yes

**ASSIGNMENT INFORMATION**

Assignee Name:: Lintec Corporation  
Street of Mailing Address:: 23-23, Honcho  
City of Mailing Address:: Itabashi-ku  
State or Province of Mailing Address:: Tokyo  
Country of Mailing Address:: Japan  
Postal or Zip Code of Mailing Address:: 1730001